



▶ Ur Hongxin Testing Technology(Shenzhen)Co., Ltd.



• Impartial • Professional ■ Accurate ■ High-tech



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# About URHX

## Abstract


Ur Hongxin Testing Technology (Shenzhen) co., Ltd. (Foxconn China Measurement Center) is a professional integrated laboratory with worldwide presences and strong R&D capabilities.

It provides fast, consistent, and accurate testing and measurement services for high-tech products design, development, and manufacturing. A nationwide network system: laboratories have been established in Shenzhen, Dongguan, Kunshan, Wuhan, Zhengzhou, Yantai, Chengdu, Chongqing, Nanning and offices have been set up in major cities across the country; Provide customers with cross regional and high-quality testing technical services and product solutions.

Its goal is to assist the growth of Foxconn enterprise group into a highly competitive global technology company in the world.



# About URHX



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Its goal is to assist the growth of Foxconn enterprise group into a highly competitive global technology company in the world.



# Quality Certificate

Obtained CMA certificate in June 2018, Certificate NO. 201819123247.

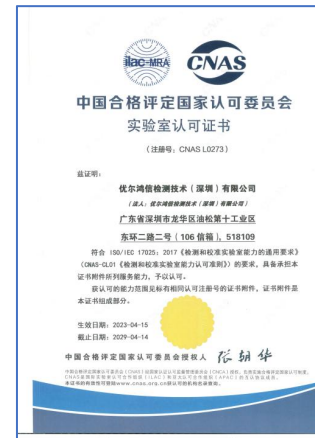
Accredited by CNAS (China National Accreditation Service for Conformity Assessment) via the ISO/IEC 17025:2005 (The General requirements for the competence of testing and calibration laboratories) since Feb 2003.

Since 2002, Ur Hongxin continue to participate in the capability validation organized by the CNAS, IIS, ASTM and other international and domestic authorities. Obtained CNAS PTP certificate in 2016, Certificate NO. PT0053. Fully ensure our technology to reach the international advanced level.

We have won recognition of many international customers, Our professional technical ability, detection ability, the results of accuracy, fairness and confidentiality have won praise of the customers!



中国认可  
国际互认  
检测  
TESTING  
CNAS L0273



# Our Tenet

**Customer satisfaction is our mission**

## Our Advantages

- Professional technical team
- Years of experience of testing and failure analysis in manufacturing industry
- Advanced equipment
- Comprehensive test solution
- Advanced testing equipment and materials technology development capability
- Master the core technology and have patents
- Service around the country
- Customer first



# Our Service

## Environmental, Mechanical, Packaging Material Reliability Testing

The first laboratory in China to be Accredited by Dell for Vibration, Shock, Drop, and Packaging Material testing

### Environment Test Laboratory

- High/Cold Storage Test
- Temp. and Humidity Cyclic Test
- Temperature Shock Test
- ESS Test
- Perspiration Resistance Test
- Salt Spray Test
- Dust Test
- Accelerated Weathering Test
- Xenon Exposure Test
- Altitude Test
- Temp. and Humidity Storage Test
- Thermal Profile Test
- Infrared Thermal Imaging
- HAST Test



### Package Test Laboratory

- Container Compression Test
- Container Stacking Test
- Bursting Strength Test
- Pallet Test
- 90° /180° Peel Adhesion Test
- Corner (Edge) Protector Test



### ■ Vibration and Shock Test Laboratory

- Vibration Test
- Shock Test
- Drop Test
- Drop-G Test
- Measure and Analysis of Vibration
- Pallet Package Drop Test
- Pallet Package Vibration Test
- Floor Vibration Measure



# Our Service

## Mobile Product Test

### Cosmetic Test

- .Chemical Resistance Test
- .Linear Abrasion Test
- .Adhesion Test
- .Pencil Hardness Test

### Torque Test Force Test

- Ball Drop Test
- Static Pressure Test
- Twist Test

### Life Test

- .Keypad/Flip Lifecycle
- .Connector Lifecycle
- .Insert & Withdraw Test

### Drop Test

- .Free Fall Drop
- .Random Drop
- .Repetitive Drop



## Highly Accelerated Life Test

### Highly Accelerated Life Test

- .AC/DC Voltage Test
- .Temperature Margin Test
- .Rapid Thermal Transition Test
- .Tri-Axial Random Vibration Test
- .Combined Test

### Highly Accelerated Stress Screen

### Highly Accelerated Stress Audit



# Our Service

## Acoustic Measurement & Analysis

- Sound Power Level Test
- Sound Pressure Level Test
- Sound Quality Evaluation
- System Vibration Test
- Electro-acoustic Test



## PCBA & PCB & Component Failure Analysis

### ■ SEM+EDS (Scanning Electron Microscope)

- IMC Inspection
- Element Analysis
- Tin Whisker Inspection



IMC Inspection



C-SAM Analysis



### ■ C-SAM (C-Type Scanning Acoustic Microscope)

- 3D OM Inspection
- Cross Section
- Dye & Pry
- IC Decapping
- Wetting Balance
- Bonding Test

- Shear Test
- Pull Test

### ■ Solder Paste Properties Test

- Viscosity Test
- Solder Tack Test
- Open Life
- Flux Content



SIR Test



X-RAY Test



### ■ Surface Insulation Resistance Test (SIR)

# Our Service

## Hazardous Substances Test

- RoHS(Cd/Pb/Hg/Cr(VI)/PBBs/PBDEs)
- Metal Elements Quantification
- Migration Element in Toy
- Halogen(F/Cl/Br)
- Phthalates(DBP/BBP/DEHP/DIBP/DIDP/DINP /DnOP/ DMEP/Dnepr)
- TBBPA
- PAHs
- HBCDD
- SCCP/MCCP
- Cyclosiloxane(D3~D10) . DMF
- Nickel Release
- PFOS/PFOA
- AZOs

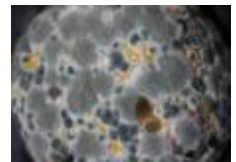


## Microbiological Test

- Mold growth Test for Electric and Electronic Products
- Evaluation for Plastic Mouldproof Effects
- Evaluation for Paints Film Mouldproof Effects
- Evaluation for Nonmetallis Gasket Materials Mouldproof Effects

### Mold Species

- |                             |                             |
|-----------------------------|-----------------------------|
| .Aspergillus Niger          | .Aspergillus Flavus         |
| .Aspergillus Terreus        | .Chaetomium Globosum        |
| .Hormoconis Resinae         | .Paecilomyces Varioti       |
| .Penicillium Funiculosum    | .Scopulariopsis Brevicaulis |
| .Trihoderma Longibrachiatum | .Penicillium Citrinum       |
| .Cladosporium Herbarum      | .Alternaria Alternaria      |
| .Aureobacidium Pullulans    | .Aureobasidium Pullulans    |

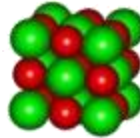
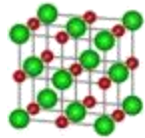


# Our Service

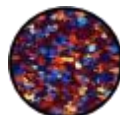
## Metal Material Test

### Microstructure

- Surface Observation
- Grain Size
- Uniformity Analysis of Carbides
- Inclusion Analysis
- Carburized Depth
- Metallographic Structure



Metallographic Structure (Brass)



Al5052 (Polarizing)



Uniformity Analysis of Carbides



Fracture Morphology

- Coating Film Thickness
- Chemical Composition
- Fracture Analysis

### Hardness

- Material/Surface/Core Vickers Hardness
- Rockwell Hardness

### Mechanical Properties

- Tensile/Yield Strength, Elongation
- Bend Testing
- Spring Force/Spring Rate
- Pulling/Pushing/Shearing Force
- Torsion



## Polymer Material Analysis

### Mechanical Properties

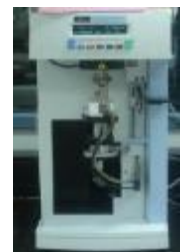
- Tensile Testing
- Flexural Testing
- Hardness Testing
- Impact Testing

### Physical Properties

- Specific Gravity
- Ash Content
- Melt Flow Index
- Color Difference

### Others

- Thermal Analysis
- Flammability Properties
- Optical Properties



# Our Service

## Test Items of Lithium Battery Materials

- Moisture
- Specific Surface Area
- PH Value (positive and negative electrode materials ,electrolyte)
- Tap Density
- Particle Size Analysis
- IC Gram Capacity
- Discharge Capacity
- Chlorinated Paraffin / CP Impurity
- Conductivity
- Density
- Acidity
- Tensile
- Puncture
- Air Permeability
- Porosity
- Areal Density



## Failure Analysis

### Metal Materials and Parts

- Fracture ,Cosmetic Defect, Corrosion, Wear, Crack, Distortion

### Polymer Materials and Plastic Parts

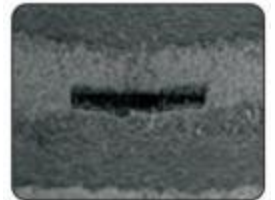
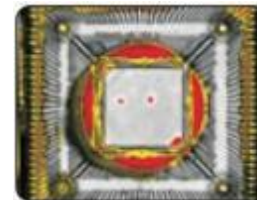
- Injection Black Spots, Plastic Fracture, Cracking, Mixed Color, In Blister, Layered, Coating Falling off, Corrosion

### PCB/PCBA

- Poor Soldering, Components Defect, Electrochemical Corrosion, PCB Defect

### Abnormal Composition

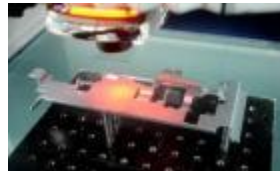
- Heterochromatic and Odor Analysis, Nozzle Material Analysis, Organic Residue, Analysis of Industrial Pharmaceutical Composition



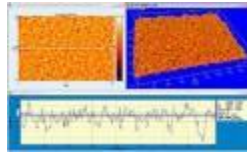
# Our Service

## Precision Measurement

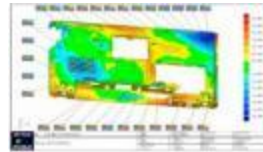
- . Dimensional Measure
- . Computer Aided Verification (CAV)/Reverse Engineering
- . Gear Test
- . Geometric Tolerance Analysis
- . Surface Roughness Test
- . 3D MicroStructure Analysis



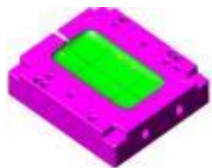
3D Optic Interferometer



3D Surface Roughness



3D Color Plots for Deviation Analysis

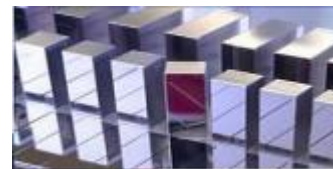


Precision Model Verification



## Equipment Calibration

- . Length Calibration
- . Electrical Calibration
- . Mass Calibration
- . Force Calibration
- . Temperature Calibration
- . Physics&Chemistry Calibration
- . Maintainance



# Our Service

## EMC Test

Accredited by NVLAP and VCCI

- Radiated Emission (3m Chamber)
- Radiated Emission (10m Chamber)
- Conducted Emission
- Harmonic Test
- Flicker Test
- ESD Test
- Radiated Susceptibility
- EFT Test
- Surge Test
- Conducted Susceptibility
- PFMF Test
- Dip Test
- Ring Wave Test



RS Test Setup(743 Chamber)



10m Chamber



NVLAP

# Our Service



## Passive & Electromechanical Component Test

### PCB

- . R-PCB
- . F-PCB

### Connector

- . Inner Connector
- . I/O Connector

### Protection Device

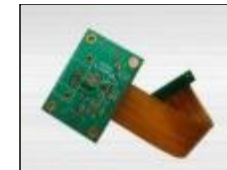
- . Thermistor
- . Fuse
- . ESD Protection Device

### Res./Cap./Ind.

- . Resistor
- . Capacitor
- . Inductor
- . Bead/filter
- . Transformer
- . RF Component

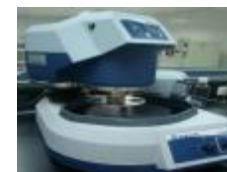
### Fre. Component

- . Crystal
- . Oscillator



## Main Service Item

- ▶ Raw Material Analysis
- ▶ Mechanical & Physical Analysis
- ▶ Electrical & Functional Test
- ▶ Life Test
- ▶ Environmental & Reliability Test
- ▶ Failure Analysis
- ▶ Integrated Validation



# Our Service

## Module Test and SI

### Signal Integrity Measurement

- . DDR/PCI/Clock/ ...
- . DVI/HDMI/DP/ ...
- . USB/SATA/PCIE/ ...
- . Power Integrity

### Power Unit

- . SPS
- . Adapter/Charger
- . Battery/Power Bank

### Storage Module

- . HDD, Optical Disc
- . Memory DIMM

### Service Items

- ▶ Functionality and Electrical
- ▶ Performance Test
- ▶ Compatibility Test
- ▶ Mechanical Test
- ▶ Reliability Test
- ▶ Optical Performance Test
- ▶ RF Performance Test
- ▶ Safety/EMC Test
- ▶ Signal Integrity Measurement
- ▶ Module FA

### Image, Acoustics Module

- . LCD Module
- . Touch Panel
- . Camera Module
- . Speaker, Microphone

### Cable, Fan

- . Power Cord
- . Data Cable
- . Fan

### Communication

- . Wi-Fi, Bluetooth
- . TV Tunnel



# Our Service

## Active Types

### ASIC/ASSP

- . CPU/MCU/ Audio/Clock/LAN/I/O

### Linear IC

- . Standard Linear ICs
- . Power Controller/ Sensors

### Digital Logic IC

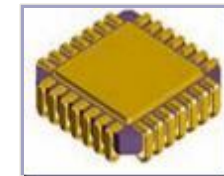
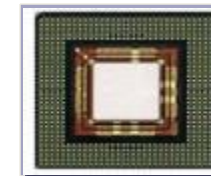
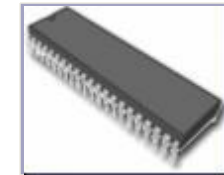
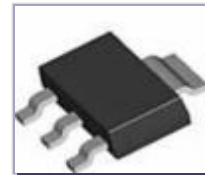
- . Standard Logic ICs/PLD

### Memory

- . EEPROM/NOR/NAND Flash /SRAM/ DRAM

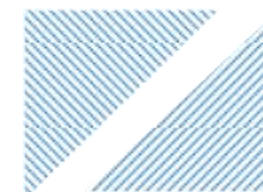
### Discrete

- . MOSFET/Transistor/ Diode/LED



## Major Services

- ▶ Function Test
- ▶ Electrical Characteristic
- ▶ Parameter Test
- ▶ ESD Rating Test
- ▶ MSL Rating Test
- ▶ Package Quality Test
- ▶ Reliability Test
- ▶ Failure Analysis
- ▶ Component Quality Verification



# Our Service

## Test of Automobile Materials and Parts

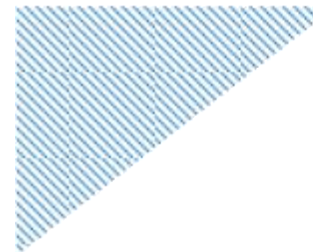
### Material Test

- .Mechanical Properties
- .Chemical Composition
- .Physical Properties
- .Thermal Properties
- .Structure Analysis
- .Size Measurement
- .Plastic Combustion Performance And Electrical Performance Test
- .Material Composition Analysis Test



### Coating Performance Test of Interior and Exterior Trim Parts

- .Gravel Impact
- .Paint Film Thickness
- .Gloss
- .Water Resistance
- .Paint Film Hardness
- .Cross-cut Test
- .Bending
- .Abrasion Resistance
- .Color Difference
- .Salt Spray
- .Solar Radiation
- .Flexibility



### Wire Harness /Connector Test

- .Environmental Stress
- .Mechanical Stress
- .Mechanical Service Life
- .Chemical Stress
- .Electrical Strength



### Cleanliness Test

# Our Service

## Environment Test

### Drinking Water Safety Test

- .Heavy Elements
- .Disinfection By-products
- .Organics
- .Microbiological Index



### Industrial Waste Water Test

- .Heavy Elements
- .pH
- .COD
- .Turbidity



### Indoor/Workplace Air Test

- .Benzene Series and Formaldehyde
- .Other Gaseous Pollution

### Gaseous Pollution Emission Test

- .Sulfur Dioxide and Nitric Oxide
- .Non-methane Total Hydrocarbon
- .PM10 and PM2.5
- .Other VOCs



# Our Service

## Proficiency Testing(PTP)

### Electrical and Electronic Products

- .High Temperature (IEC 60068-2-2, GB/T 2423.2)
- .Vibration (IEC 60068-2-6, GB/T 2423.10)
- .Shock (IEC 60068-2-27, GB/T 2423.5)
- .Low Temperature (IEC 60068-2-1, GB/T 2423.1)

### Measurement

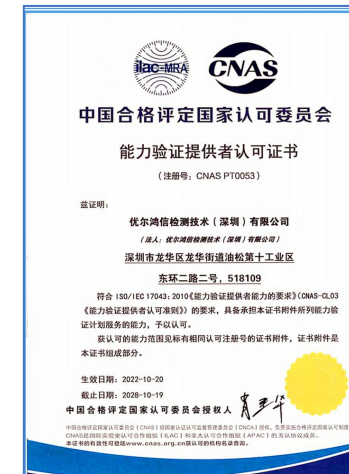
- . Length of Common Parts (ASME Y14.5, GB/T 3177)
- .Surface Roughness of Multi Scribed Template (GB/T 10610)
- .True Roundness of Common Parts (ASME Y14.5, GB/T 1958)

### Plastic Test

- .Decabromodiphenyl Ether (IEC62321-6)
- .Cr(VI) (EC 62321-7-2)
- .Cl, Br(BS EN14582)
- .Pb, Cd , Hg(IEC 62321-5)
- .Density (GB/T 1033.1, ISO 1183-1, ASTM D 792)
- .Tensile Strength (GB/T 1040.1, GB/T 1040.2, ISO 527.1, ISO 527.2, ASTM D 638)



中国认可  
能力验证  
PROFICIENCY TESTING  
CNAS PT0053



★ Branch分支机构  
● Headquarter总部

# Service Network

全球热线：

**400-845-2188**

Dial our corporate 400 hotline to get direct access to testing service outlets across major Chinese cities. We maintain coordinated collaboration with our overseas laboratories in Vietnam, enabling unified coordination and rapid response for all domestic and international testing requests.

## 深圳总部

Tel: 0755-29846730/13266749144

E-Mail: li.wang@foxconn.com

ADD: 深圳市龙华镇油松第十工业区  
东环二路二号富士康华南检测  
中心E11栋

## 昆山检测中心

Tel: 0512-83666888-76633/18676742563

E-Mail: qianghua.yang@foxconn.com

ADD: 江苏省昆山市南淞路299号富  
士康科技园内

## 重庆检测中心

Tel: 023-61702888/16675391445

E-Mail: tao.t.zou@foxconn.com

ADD: 重庆市沙坪坝区西永微电园东区  
1路1号富士康科技园内

## 郑州检测中心

Tel: 027- 81933888-22403/17688161454

E-Mail: jin-wei.cao@foxconn.com

ADD: 河南省郑州市航空港区长安路东侧  
综合保税区富士康科技园内

## 东莞松山湖检测中心

Tel: 0755-28129588-28394

E-Mail: li.wang@foxconn.com

ADD: 广东省东莞市寮步镇松湖华科孵化  
园三栋105富士康科技园内

## 烟台检测中心

Tel: 0535-2168888-38512/18664568527

E-Mail: cmc-yt-li.qy@foxconn.com

ADD: 山东省烟台经济技术开发区  
出口加工区富士康科技园内

## 武汉检测中心

Tel: 027- 81933888-22403/17688161454

E-Mail: jin-wei.cao@foxconn.com

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士康科技园内

## 成都检测中心

Tel: 028-68522005/16675391445

E-Mail: tao.t.zou@foxconn.com

ADD: 四川省成都市高新区西部园区  
合作路888号富士康科技园内

## 天津检测中心

Tel: 0512-83666888-76633/18676742563

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## 南宁检测中心

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51号富士康科技园内

全球热线

400-845-2188

## 01 公司基本信息

优尔鸿信检测技术(深圳)有限公司,  
英文名称为Ur Hongxin Testing Technology  
(Shenzhen) Co., Ltd.。

优尔鸿信检测  
技术(深圳)  
有限公司

## 02 服务网站

电子检测网站: <https://www.urhxee.com>  
材料检测网站: <https://www.urhxcmc.com>  
化学分析网站: <https://www.urhxchem.com>  
汽车材料零部件测试网站: <https://www.urhxauto.com>  
PTP 能力验证站点: <https://www.urhxcmc.com/resources/index.html>

## 自媒体 @优尔鸿信



## 研发总部位置

其研发总部位于深圳龙华区东环二路二  
号富士康科技集团华南检测中心E11栋。